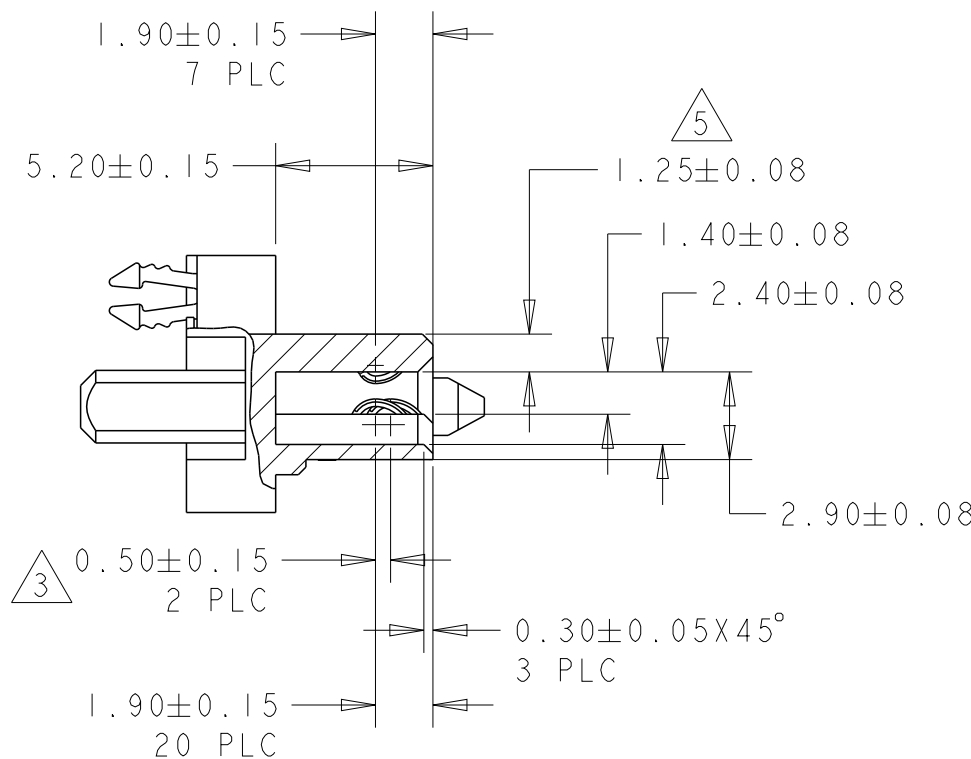
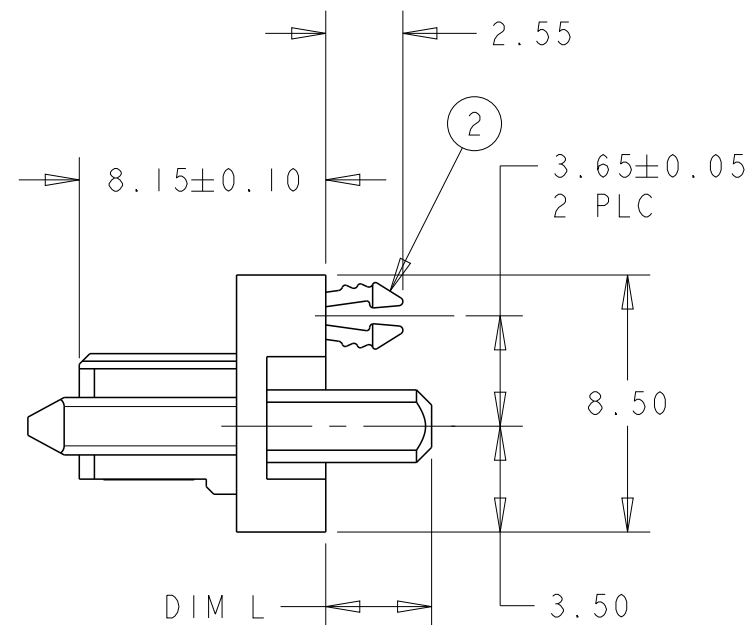
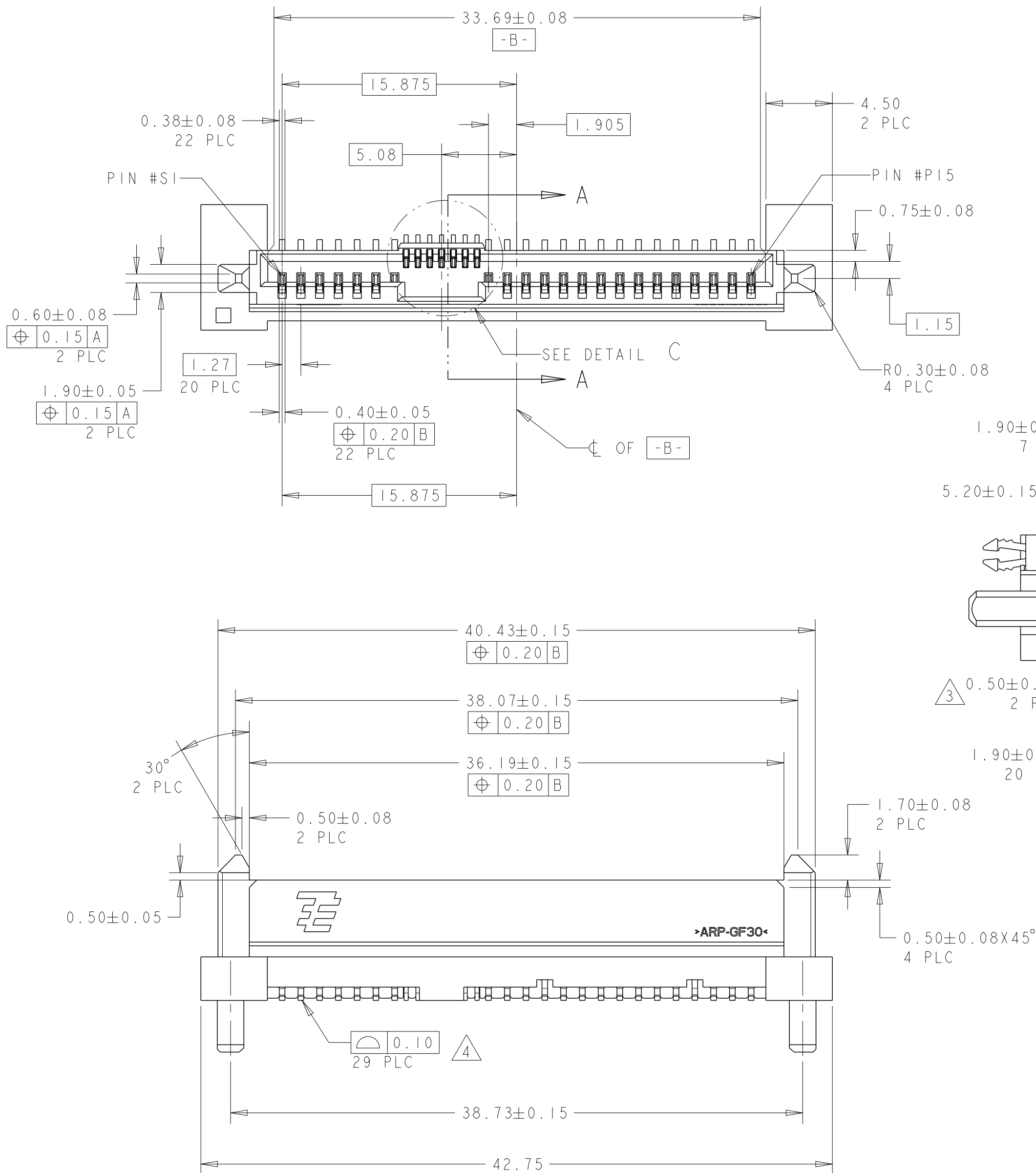


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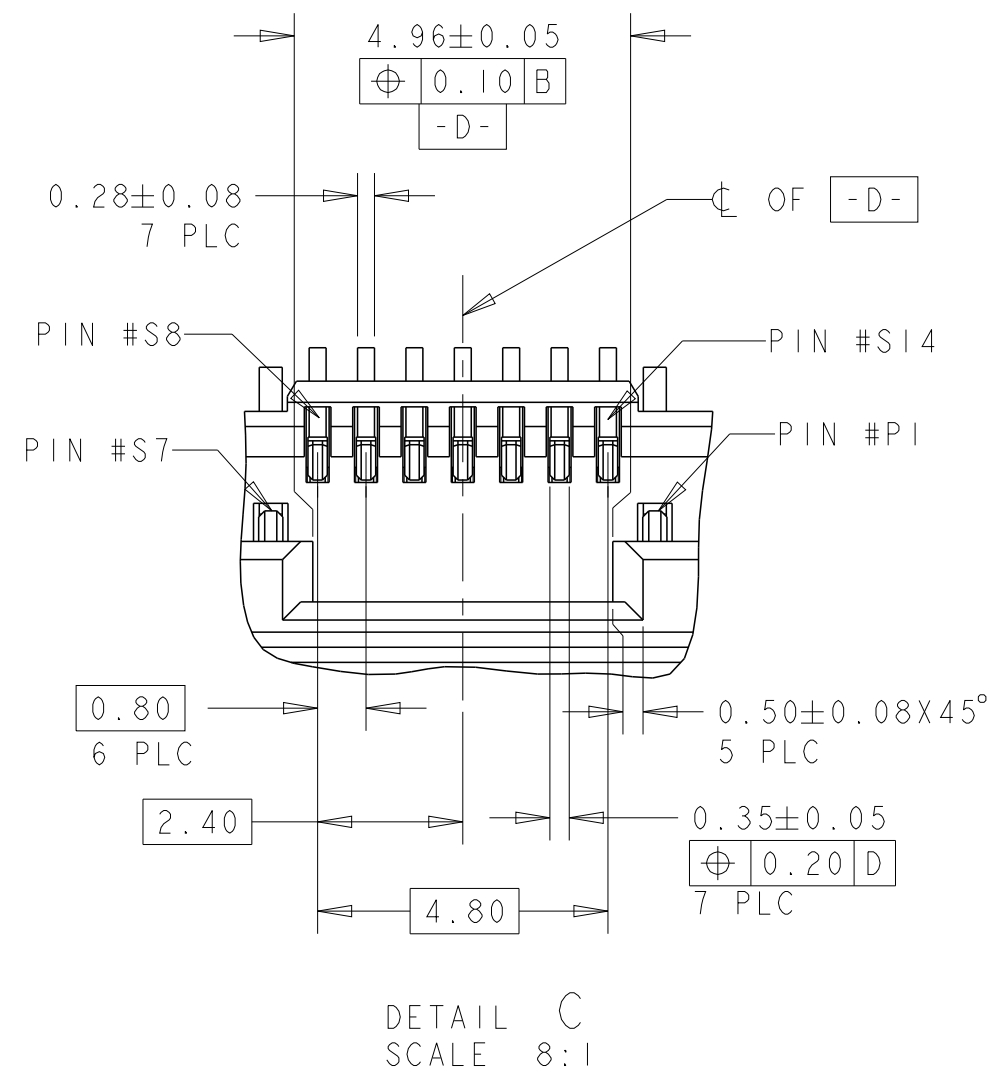
DWG NO
1735105

USED ON
-



NOTES:

- 1 MATERIAL:
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0,
COLOR: BLACK
CONTACT: COPPER ALLOY
BOARDLOCK: COPPER ALLOY
- 2 FINISH:
CONTACT AREA: MIN 0.76um GOLD PLATING
SOLDERTAIL: MIN 2.54um MATTE TIN PLATING
UNDERPLATE: MIN 1.27um NICKEL PLATING
- 3 PIN #P4 AND #PI2 ONLY
- 4 SOLDERTAIL TO BE 0.05 MAX ABOVE AND
0.10 MAX BELOW DATUM E
- 5 1.33 MAX MEASURED AT -C-

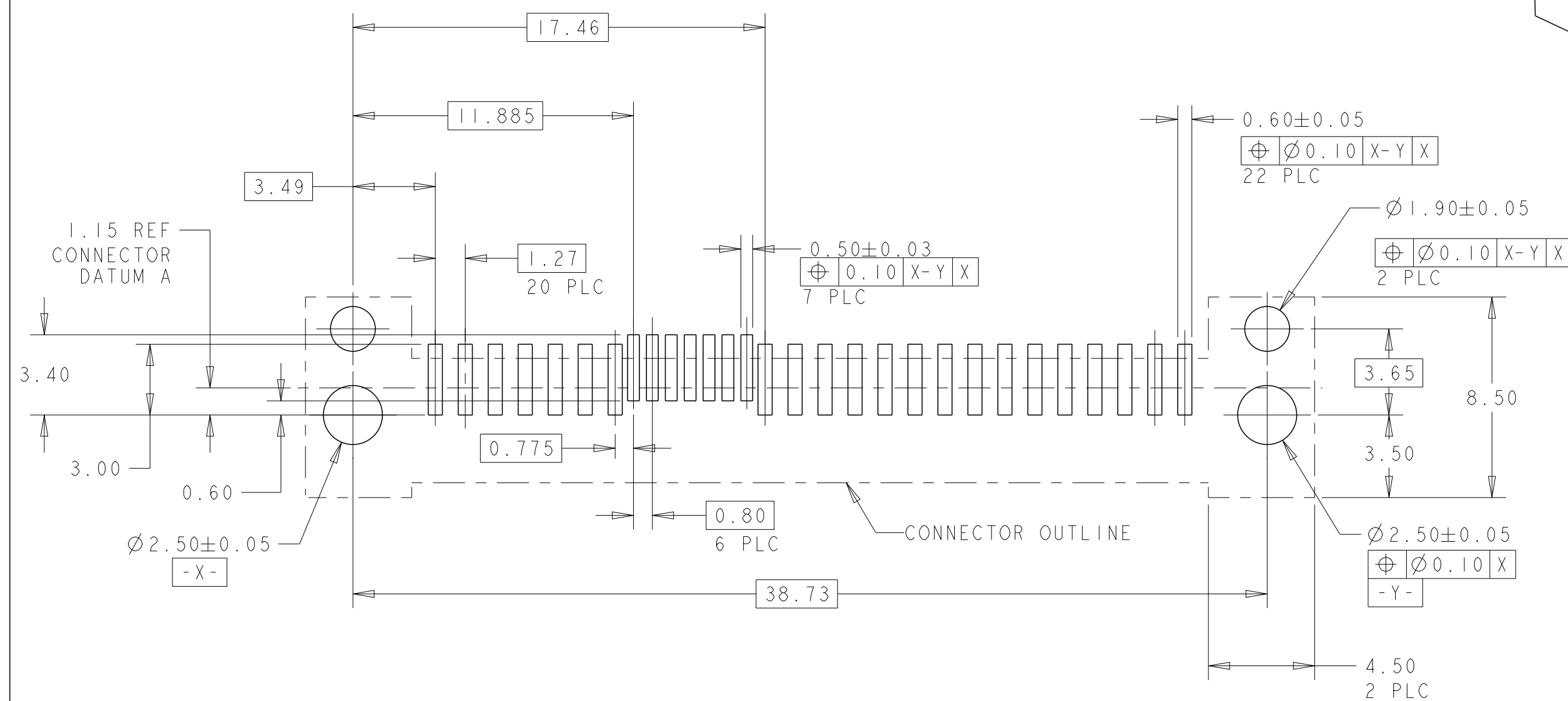
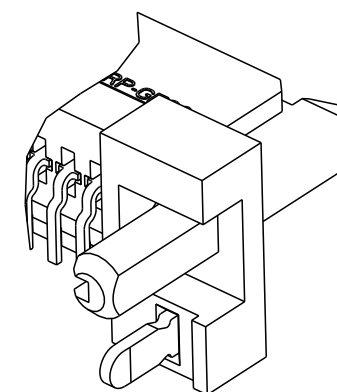
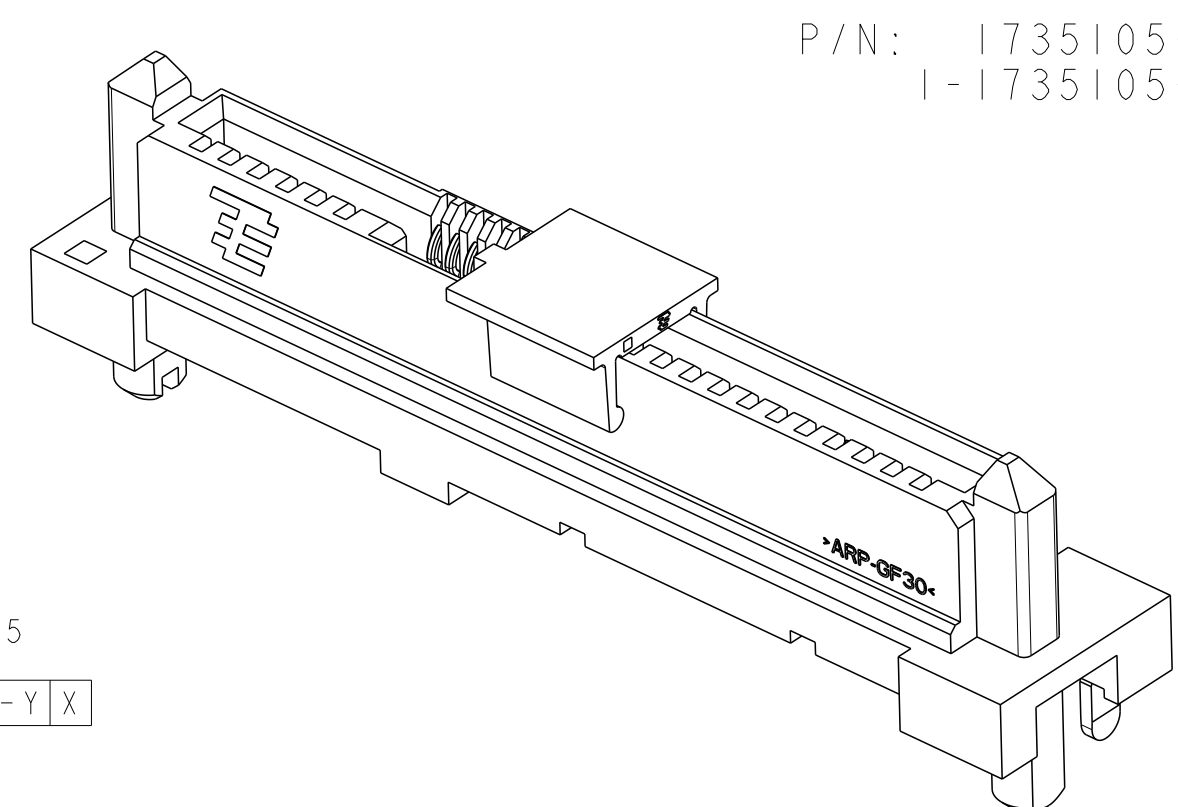
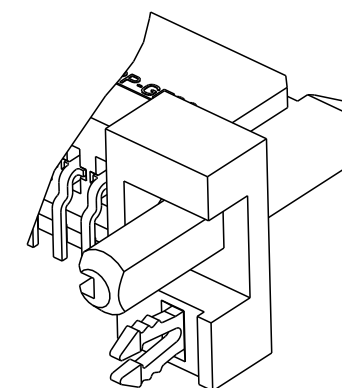
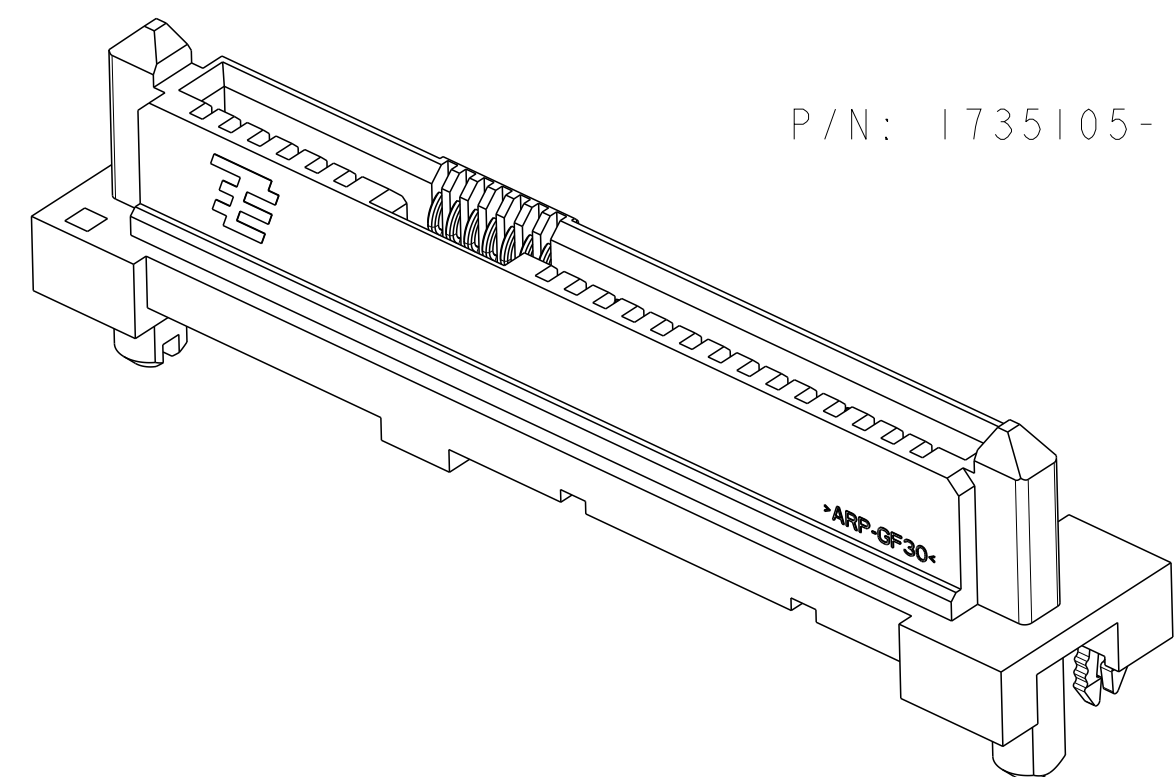
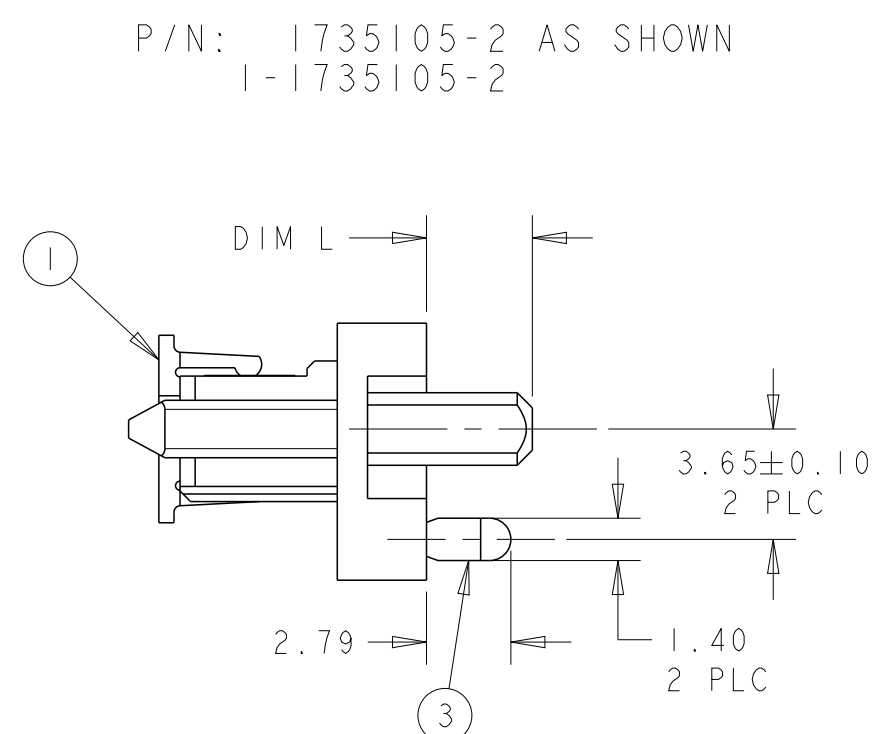


TAPE & REEL	ZIF TYPE 3	3.50	YES	I-1735105-2
TRAY	ZIF TYPE 3	3.50	YES	1735105-2
TRAY	FORK TYPE 2	3.50	NO	1735105-1
PACKAGING	BOARDLOCK	DIM L	PICK-UP CAP 1	PART NUMBER

C	REVISED PER ECO-14-008474	05JUN2014	BL	JY
LTR	REVISION RECORD	DATE	DWN	APVD

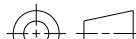
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:
mm	0 PLC ±- 1 PLC ±- 2 PLC ±0.20 3 PLC ±- 4 PLC ±-
ANGLES	3°
SURFACE TEXTURE	✓

DWN	29JUL2005	MATERIAL		HEAT TREAT	-
SK LEAW			-		
CHK	29JUL2005	 TE Connectivity			
SF LEONG					
APVD	29JUL2005				
SF LEONG					
NAME SAS BACKPLANE RECEPTACLE, VERTICAL, SMT					
SCALE	SIZE	DRAWING NO	SHEET	REV	
4:1	A2	1735105	1 OF 2	C	



RECOMMENDED PCB LAYOUT
SCALE 5:1

-	SEE SHEET 1	-	-	-
LTR	REVISION RECORD	DATE	DWN	APR

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED	
mm			
	0 PLC	±-	
	1 PLC	±-	
	2 PLC	±0.20	
	3 PLC	±-	
	4 PLC	±-	
ANGLES± 3°			
SURFACE TEXTURE			

DWN	29JUL2005	MATERIAL	TBD	HEAT TREAT	-
SK LEAW			-		-
CHK	29JUL2005			TE Connectivity	
SF LEONG					
APVD	29JUL2005				
SF LEONG		NAME SAS BACKPLANE RECEPTACLE, VERTICAL, SMT			
SCALE	SIZE	DRAWING NO	SHEET	OF	REV
4:1	A2	1735105	2	2	C